

Amendments to the Specification

Please amend the first paragraph on page 1 as follows:

This is a Continuation-in-Part application of ~~MEG00-005B~~, serial number 10/278,106, filed on 10/22/02, now U.S. Patent 6,374,563, which is a divisional of ~~MEG00-005~~, serial number 09/691,497, filed on 10/18/2000, now U.S. Patent 6,495,442, assigned to a common assignee.

Please replace the last paragraph on page 12 with the following:

U.S. Patent 6,383,916, ~~assigned to a common assignee as the current invention~~, teaches an Integrated Circuit structure where re-distribution and interconnect metal layers are created in layers of dielectric over the passivation layer of a conventional Integrated Circuit (IC). A layer of passivation is deposited over the IC, a thick layer of polymer is alternately deposited over the surface of the layer of passivation, and thick, wide metal lines are formed over the passivation.